ABSTRACT

Name of Institution: De La Salle University – Dasmariñas

Address: Dasmariñas, Cavite

Title: Reducing the Overlapping Testing in Reliability Measurements Laboratory of Philips Semiconductors Philippines Incorporated

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Objectives of the Study:

A. **General:**

To eliminate the overlapping of tests in the Reliability Measurements Laboratory

B. **Specific:**

- To increase productivity by 25%
- To lessen time consumed in testing by 50%

Scope and Limitation:

The researcher was focused on the problem of overlapping between the High Temperature Storage (HTS) and the High Temperature Reverse Bias (HTRB).

Methodology:

The researcher was conducted a interview on the Laboratory Assistant, Data Gathering and Observation on the 2 heat tester equipments

Conclusion:

The researcher conclude must avoid the test redundancy to solve the overlapping test.

Recommendation:

The researcher recommend that must have a single test in the heat tester especially when the same condition has given.